

APPARATUS AND METHOD FOR STRIP SOLDER PLATING

Abstract

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The present invention relates to an apparatus for solder plating at least one work piece comprises a frame, a carrier mounted on the frame for rotation about a vertical axis and having a plurality of work piece holders, and a plurality of process stations arranged in a circular array, at least some of said process stations including electrolytic solutions. The
10 work piece holders have top and bottom fingers for holding respective work pieces, indexing means for moving the carrier, a plurality of first contacts and a plurality of second contacts wherein the indexing means is operable to cause selected first and second contacts to engage one another when the carrier is in said lowered position to thereby enable electrical connections to be established with the process stations which include said
15 electrolytic solutions. The present invention further relates to a method for strip solder plating.

FIG. 1